SDAS167C - APRIL 1982 - REVISED NOVEMBER 1999

- D-Type Flip-Flops in a Single Package With 3-State Bus Driving True Outputs
- Full Parallel Access for Loading
- Buffered Control Inputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs

description

These octal D-type edge-triggered flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

(1	TOP VIEW)	
OE [1Q [] 1D [] 2Q []	1 20 2 19 3 18 4 17 5 16] V _{CC}] 8Q] 8D] 7D] 7Q
h aa		haa

SN54ALS374A, SN54AS374... J PACKAGE SN74ALS374A. SN74AS374... DW OR N PACKAGE

2D [4] 7D
2Q [5	16] 7Q
3Q [6] 6Q
3D [7] 6D
4D [8	13] 5D
4Q [9] 5Q
GND [10	11] CLK

SN54ALS374A, SN54AS374...FK PACKAGE (TOP VIEW)

01 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	20	
	19	
2D] 4	[`] 18 [8D
2Q 5	17	7D
3Q 🗍 6	16	7Q
2D] 4 2Q] 5 3Q] 6 3D] 7 4D] 8	15	6Q
4D 18	14	6D
	3]	
CLK 0 50 ND 50 ND	25	

OE does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54ALS374A and SN54AS374 are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS374A and SN74AS374 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)								
	INPUTS	OUTPUT						
OE	CLK	D	Q					
L	\uparrow	Н	Н					
L	\uparrow	L	L					
L	H or L	Х	Q ₀					
н	Х	Х	Z					



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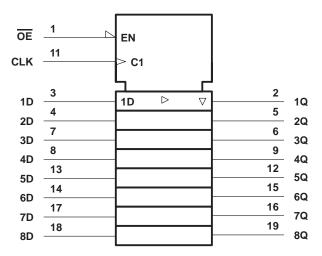
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



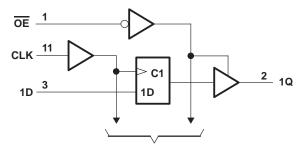
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SDAS167C – APRIL 1982 – REVISED NOVEMBER 1999

logic symbol[†]



logic diagram (positive logic)



To Seven Other Channels

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V ₁	–0.5 V to 7 V
Voltage applied to a disabled 3-state output	–0.5 V to 5.5 V
Package thermal impedance, θ _{JA} (see Note 1): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

		SN54ALS374A			SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C



SDAS167C - APRIL 1982 - REVISED NOVEMBER 1999

DADAMETED	TEST CONDITIONS		SN5	4ALS374	1A	SN7	LINUT		
PARAMETER	IESI CC	INDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lı = -18 mA			-1.5			-1.5	V
	V _{CC} = 4.5 V to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} -2			V _{CC} -2			
VOH		I _{OH} = -1 mA	2.4	3.3					V
	$V_{CC} = 4.5 V$	I _{OH} = -2.6 mA				2.4	3.2		
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	0.4 V
VOL	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	VI = 0.4 V			-0.2			-0.2	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		11	20		11	19	
Icc	$V_{CC} = 5.5 V$	Outputs low		19	28		19	28	mA
		Outputs disabled		20	31		20	31	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			SN54AL	S374A	SN74AL	S374A	UNIT
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency	-		30		35	MHz
tw	Pulse duration	CLK high or low	16.5		14		ns
t _{su}	Setup time	Data before CLK↑	10		10		ns
th	Hold time	Data after CLK↑	4		0		ns

switching characteristics over recommended operating conditions (unless otherwise noted (see Figure 3)

PARAMETER	FROM	то	SN54AL	S374A	SN74AL	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
fmax			30		35		MHz
^t PLH		0	3	14	3	12	ns
^t PHL	CLK	Q	5	17	5	16	115
^t PZH	OE	0	3	18	3	17	ns
^t PZL	UE	Q	5	21	5	18	115
^t PHZ	ŌĒ	Q	1	11	1	10	200
^t PLZ	UE		2	19	2	18	ns



SDAS167C - APRIL 1982 - REVISED NOVEMBER 1999

recommended operating conditions

		SI	154AS37	'4	SI	SN74AS374		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-12			-15	mA
IOL	Low-level output current			32			48	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST OF	NDITIONS	SN	154AS374	4	SN	74AS374	4	UNIT
PARAMETER	TEST CC	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lı = -18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2			
VOH		I _{OH} = -12 mA	2.4	3.2					V
	$V_{CC} = 4.5 V$	I _{OH} = -15 mA				2.4	3.3	3 4 0.5 50 μ -50 μ	
Ve		I _{OL} = 32 mA		0.29	0.5				V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA					0.34	0.5	v
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μA
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μA
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
IIН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
OE, CLK					-0.5			-0.5	
I _{IL} Data	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-3			-2	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
		Outputs high		77	120		77	120	
ICC	V _{CC} = 5.5 V	Outputs low		84	128		84	128	mA
		Outputs disabled		84	128		84	128	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			SN54A	S374	SN74A	S374	UNIT
			MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency			100*		125	MHz
	Pulse duration	CLK high	5.5*		4		
tw	Pulse duration	CLK low	3*		3		ns
t _{su}	Setup time	Data before CLK↑	3*		2		ns
th	Hold time	Data after CLK↑	3*		2		ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.



SDAS167C - APRIL 1982 - REVISED NOVEMBER 1999

switching characteristics over recommended operating conditions (unless otherwise noted) (see Figure 3)

PARAMETER	FROM	то	SN54A	S374	SN74A	UNIT	
FARAIVIETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
f _{max}			100*		125		MHz
^t PLH	CLK	0	3	11	3	8	ns
^t PHL	ULK	Q	4	11.5	4	9	
^t PZH	OE	0	2	7	2	6	-
^t PZL	UE UE	Q	3	11	3	10	ns
^t PHZ	OE	0	2	10	2	6	00
^t PLZ		Q	2	7	2	6	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.



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APPLICATION INFORMATION

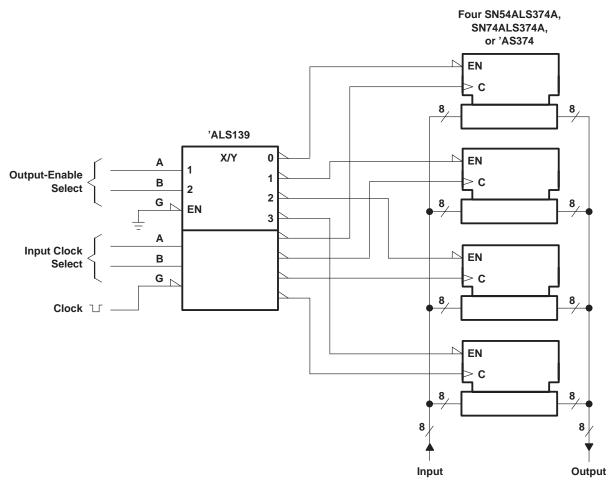
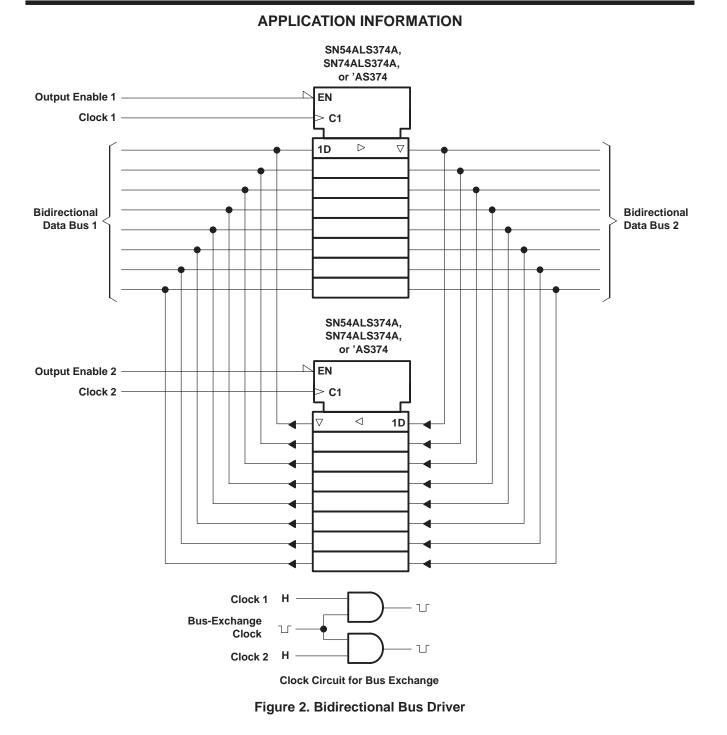


Figure 1. Expandable 4-Word by 8-Bit General File Register



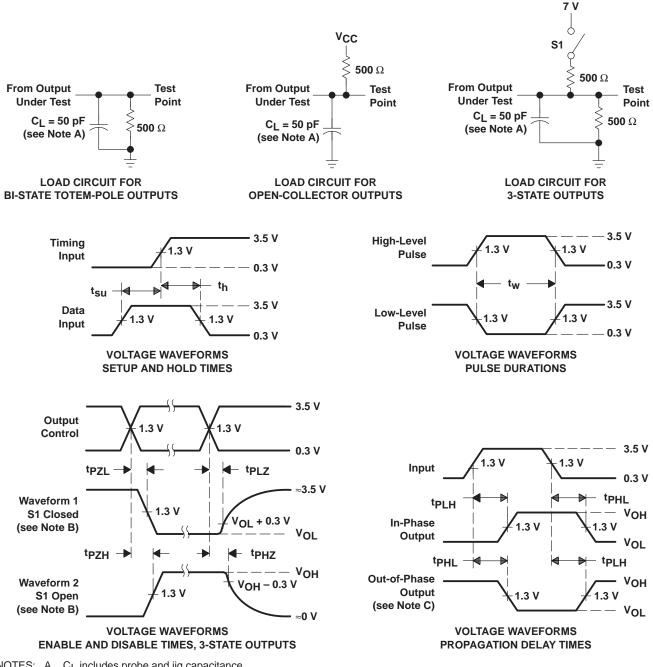
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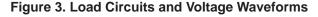
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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CI includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.







PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9756201QRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9756201QR A SNJ54AS374J	Samples
83020022A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	83020022A SNJ54ALS 374AFK	Samples
8302002RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302002RA SNJ54ALS374AJ	Samples
8302002SA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302002SA SNJ54ALS374AW	Samples
JM38510/37204B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type		JM38510/ 37204B2A	Samples
JM38510/37204BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type		JM38510/ 37204BRA	Samples
M38510/37204B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37204B2A	Samples
M38510/37204BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37204BRA	Samples
SN54ALS374AJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type		SN54ALS374AJ	Samples
SN54AS374J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54AS374J	Samples
SN74ALS374ADW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS374A	Samples
SN74ALS374ADWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS374A	Samples
SN74ALS374AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS374AN	Samples
SN74ALS374ANSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS374A	Samples
SN74AS374N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS374N	Samples
SNJ54ALS374AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	83020022A SNJ54ALS 374AFK	Samples

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SNJ54ALS374AJ	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302002RA SNJ54ALS374AJ	Samples
SNJ54ALS374AW	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302002SA SNJ54ALS374AW	Samples
SNJ54AS374J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9756201QR A SNJ54AS374J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS374A, SN54AS374, SN74ALS374A, SN74AS374 :

- Catalog : SN74ALS374A, SN74AS374
- Military : SN54ALS374A, SN54AS374

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

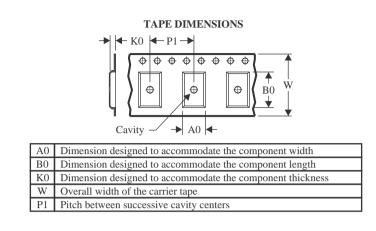


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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS374ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS374ANSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

16-Jan-2023



*All dimensions are nominal

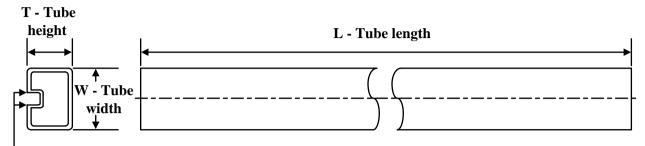
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS374ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS374ANSR	SO	NS	20	2000	367.0	367.0	45.0

TEXAS INSTRUMENTS

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TUBE



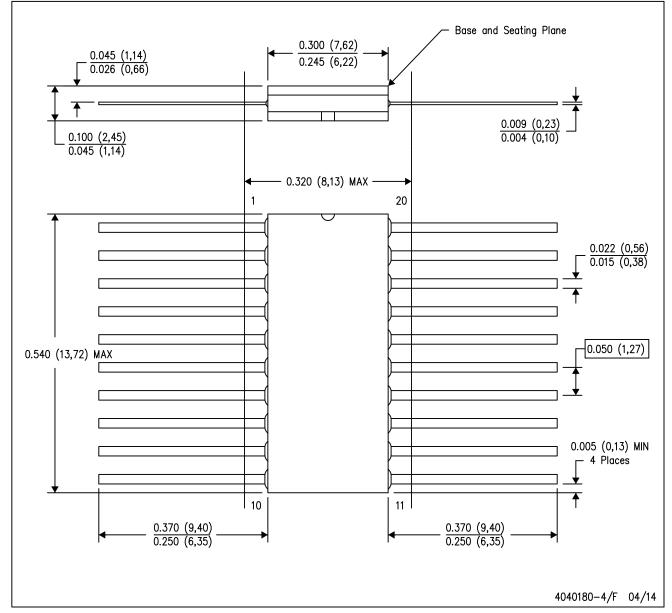
- B - Alignment groove width

*All dimensions are nomin	nal
---------------------------	-----

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
83020022A	FK	LCCC	20	1	506.98	12.06	2030	NA
8302002SA	W	CFP	20	1	506.98	26.16	6220	NA
JM38510/37204B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/37204B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74ALS374ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ALS374AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74AS374N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS374AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54ALS374AW	W	CFP	20	1	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK 20

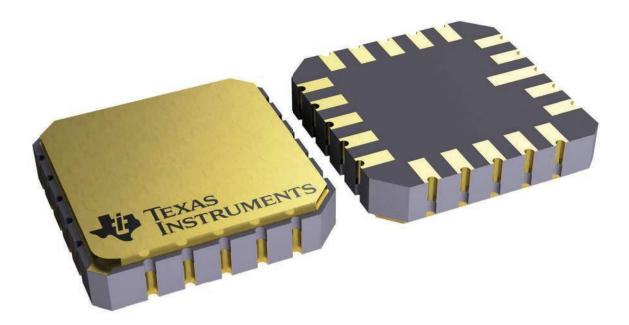
8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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